- Package Options Include Plastic "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

description

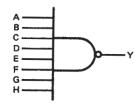
These devices contain a single 8-input NAND gate.

The SN5430, SN54LS30, and SN54S30 are characterized for operation over the full military range of $-55\,^{\circ}\text{C}$ to $125\,^{\circ}\text{C}$. The SN7430, SN74LS30, and SN74S30 are characterized for operation from $0\,^{\circ}\text{C}$ to $70\,^{\circ}\text{C}$.

FUNCTION TABLE

INPUTS A THRU H All inputs H One or more inputs L	OUTPUT Y
All inputs H One or more inputs L	L H

logic diagram

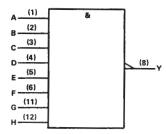


positive logic

$$Y = \overline{A \cdot B \cdot C \cdot D \cdot E \cdot F \cdot G \cdot H} \quad \text{or}$$

$$Y = \overline{A} + \overline{B} + \overline{C} + \overline{D} + \overline{E} + \overline{F} + \overline{G} + \overline{H}$$

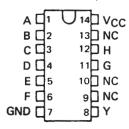
logic symbol†



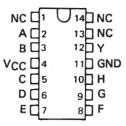
[†]This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for D, J, N, and W packages.

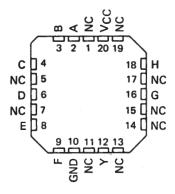
SN5430 . . . J PACKAGE
SN54LS30, SN54S30 . . . J OR W PACKAGE
SN7430 . . . N PACKAGE
SN74LS30, SN74S30 . . . D OR N PACKAGE
(TOP VIEW)



SN5430 . . . W PACKAGE (TOP VIEW)

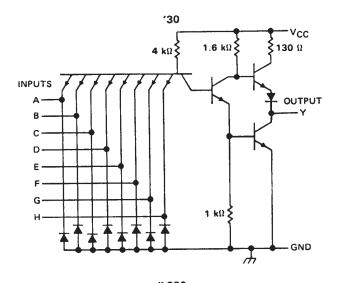


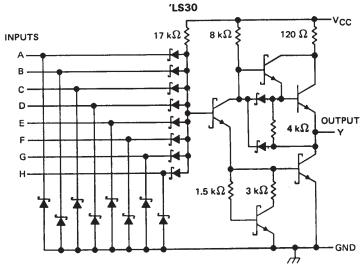
SN54LS30, SN54S30 . . . FK PACKAGE (TOP VIEW)

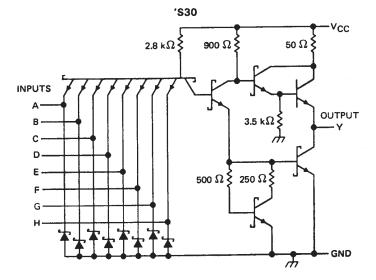


NC - No internal connection

schematics (each gate)







Resistor values shown are nominal.



SDLS099 - DECEMBER 1983 - REVISED MARCH 1988

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)	7 V
Input voltage	5.5 V
Operating free-air temperature range: SN5430	-55°C to 125°C
SN7430	0°C to 70°C
Storage temperature range	-65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

			SN5430)	SN7430 MIN NOM MAX 4.75 5 5.25			
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	٧
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			8.0			0.8	V
Іон	High-level output current			- 0.4			- 0.4	mA
loL	Low-level output current			16			16	mA
TA	Operating free-air temperature	- 55		125	0		70	°c

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	TEST CONDITIONS †			SN5430			SN7430		
PARAMETER			MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT
VIK	V _{CC} = MIN, I _I = - 12 mA				- 1.5			- 1.5	٧
Voн	V _{CC} = MIN, V _{IL} = 0.8 V,	1 _{OH} = - 0.4 mA	2.4	3.4		2.4	3.4		V
VOL	V _{CC} = MIN, V _{IH} = 2 V,	I _{OL} = 16 mA		0.2	0.4		0.2	0.4	٧
11	V _{CC} = MAX, V _I = 5.5 V				1			1	mA
¹ ІН	V _{CC} = MAX, V _I = 2.4 V				40			40	μА
IIL.	V _{CC} = MAX, V _I = 0.4 V				- 1.6			- 1.6	mA
IOS§	V _{CC} = MAX		- 20		- 55	- 18		- 55	mA
Iссн	V _{CC} = MAX, V _I = 0			. 1	2		1	2	mA
1CCL	V _{CC} = MAX, V _I = 4.5 V			3	6		3	6	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, VCC = 5 V, TA = 25°C (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS		ТҮР	MAX	UNIT
tpLH					13	22	ns
tPHL	Any	Υ	$R_L = 400 \Omega$, $C_L = 15 pF$		8	15	ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.



[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

[§] Not more than one output should be shorted at a time.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)	
Input voltage	7 V
Operating free-air temperature range: SN54LS30	-55°C to 125°C
SN74LS30	
Storage temperature range	-65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

			SN54LS	54LS30		SN74LS30		
		MIN	MIN NOM MAX		MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	٧
VIH	High-level input voltage	2	· · · · · · · · · · · · · · · · · · ·		2			٧
VIL	Low-level input voltage			0.7			0.8	٧
ЮН	High-level output current			- 0.4			- 0.4	mA
lOL	Low-level output current			4			8	mA
TA	Operating free-air temperature	- 55		125	0		70	°c

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		TEST CONDITIONS †			SN54LS30			SN74LS30			
PARAMETER		TEST CONDIT	TONS I	MIN	TYP‡	MAX	MIN	TYP‡	MAX	UNIT	
VIK	V _{CC} = MIN,	I ₁ = - 18 mA				- 1.5			- 1.5	٧	
Voн	V _{CC} = MIN,	VIL = MAX,	I _{OH} = - 0.4 mA	2.5	3.4		2.7	3.4		٧	
	V _{CC} = MIN,	V _{IH} = 2 V,	I _{OL} = 4 mA		0.25	0.4			0.4	v	
VOL	V _{CC} = MIN,	V _{1H} = 2 V,	I _{OL} = 8 mA					0.25	0.5		
. Iq	V _{CC} = MAX,	V ₁ = 7 V				0.1			0.1	mΑ	
Чн	V _{CC} = MAX,	V _I = 2.7 V				20			20	μА	
IIL	V _{CC} = MAX,	V ₁ = 0.4 V				- 0.4			- 0.4	mA	
I _{OS} §	V _{CC} = MAX			- 20		- 100	- 20		– 100	mA	
Іссн	V _{CC} = MAX,	V _I = 0			0.35	0.5		0.35	0.5	mA	
ICCL	V _{CC} = MAX,	V _I = 4.5 V			0.6	.1.1		0.6	1.1	mA	

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, VCC = 5 V, TA = 25°C (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
tPLH	A = 1 /	V	B 240 C 1505		8	15	ns
t _{PHL}	Any	,	$R_L = 2 k\Omega$, $C_L = 15 pF$		13	20	ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.



 $[\]ddagger$ All typical values are at $V_{CC} = 5 \text{ V}, T_A = 25^{\circ}\text{C}$

[§] Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note 1)	7 V
Input voltage	5.5 V
Operating free-air temperature range: SN54S30	-55°C to 125°C
SN74S30	0°C to 70°C
Storage temperature range	

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

			SN54S3	80		SN74S	30	UNIT
		MIN	MIN NOM MA	MAX	MIN	NOM	MAX	ORTI
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	٧
VIH	High-level input voltage	2			2			٧
VIL	Low-level input voltage			0.8			8.0	V
Іон	High-level output current			- 1			- 1	mA
loL	Low-level output current			20			20	mA
TA	Operating free-air temperature	55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		SN54S30	SN74S30	UNIT
PARAMETER	TEST CONDITIONS †	MIN TYP\$ MAX	MIN TYP‡ MAX	CIVIT
VIK	V _{CC} = MIN, I _I = -18 mA	-1.2	-1.2	٧
Voн	V _{CC} = MIN, V _{IL} = 0.8 V, I _{OH} = -1 mA	2.5 3.4	2.7 3.4	٧
V _{OL}	V _{CC} = MIN, V _{IH} = 2 V, I _{OL} = 20 mA	0.5	0.5	٧
. 11	V _{CC} = MAX, V _I = 5.5 V	1	1	mA
ЧН	V _{CC} = MAX, V _I = 2.7 V	50	50	μΑ
اړر	V _{CC} = MAX, V _I = 0.5 V	-2	-2	mA
I _{OS} §	V _{CC} = MAX	-40 -100	-40 -100	mA
Іссн	V _{CC} = MAX, V _i = 0	3 5	3 5	mA
ICCL	V _{CC} = MAX, V _I = 4.5 V	5.5 10	5.5 10	mA

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions. ‡ All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

switching characteristics, V_{CC} = 5 V, T_A = 25°C (see note 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONI	MIN	TYP	MAX	UNIT	
^t PLH	Any Y	$R_L = 280 \Omega$,	C ₁ = 15 pF		4	6	ns	
^t PHL		Y	n 200 12,	C[- 13 bi		4.5	7	ns
tPLH			R _L = 280 Ω,	C _L = 50 pF		5.5		ns
^t PHL						6.5		ns

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.



[§] Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.



PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-9679201Q2A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
5962-9679201QCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
5962-9679201QCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
5962-9679201QDA	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
5962-9679201QDA	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30009B2A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30009B2A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30009BCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30009BCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30009BDA	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30009BDA	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30009SCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30009SCA	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30009SDA	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
JM38510/30009SDA	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
SN5430J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SN5430J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SN54LS30J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SN54LS30J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SN54S30J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SN54S30J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SN7430N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN7430N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS30D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS30D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS30DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS30DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS30DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS30DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS30DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS30DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS30J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN74LS30J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN74LS30N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS30N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC





26-Sep-2005

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74LS30N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS30N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74LS30NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS30NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS30NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS30NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS30NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS30NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74S30D	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI
SN74S30D	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI
SN74S30DR	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI
SN74S30DR	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI
SN74S30J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN74S30J	OBSOLETE	CDIP	J	14		TBD	Call TI	Call TI
SN74S30N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74S30N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SNJ5430J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ5430J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ5430W	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ5430W	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS30FK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS30FK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS30J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS30J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS30W	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS30W	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54S30FK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54S30FK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54S30J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54S30J	ACTIVE	CDIP	J	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54S30W	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC
SNJ54S30W	ACTIVE	CFP	W	14	1	TBD	Call TI	Level-NC-NC-NC

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check



PACKAGE OPTION ADDENDUM

26-Sep-2005

http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB



FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AB.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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